

Bottom Port PDM Digital Output Multi-Mode Microphone with Ultrasonic Mode

GENERAL DESCRIPTION

The ICS-41352 is a multi-mode, low noise digital MEMS microphone in a small package. The ICS-41352 consists of a MEMS microphone element and an impedance converter amplifier followed by a fourth-order Σ - Δ modulator. The digital interface allows the pulse density modulated (PDM) output of two microphones to be time multiplexed on a single data line using a single clock.

The ICS-41352 has multiple modes of operation: Ultrasonic, Low-Power (AlwaysOn), Standard and Sleep. The ICS-41352 has high SNR in all operational modes. It has 120 dB SPL AOP in all performance modes.

In Ultrasonic Mode, the ICS-41352 has an extended ultrasonic response up to 85 kHz with high SNR.

The ICS-41352 is available in a small 3.5 × 2.65 × 0.98 mm surface-mount package. It is reflow solder compatible with no sensitivity degradation.

APPLICATIONS

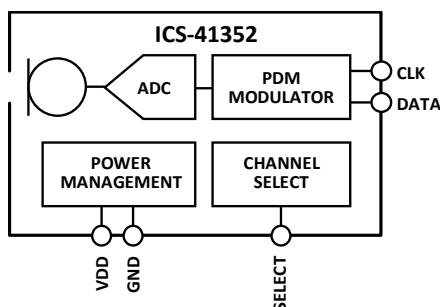
- Smartphones
- Microphone Arrays
- Tablet Computers
- Cameras
- Bluetooth Headsets
- Notebook PCs
- Security and Surveillance

FEATURES

SPEC	LOW-POWER MODE	STANDARD MODE	ULTRASONIC MODE
Sensitivity	-26 dB FS \pm 1 dB	-26 dB FS \pm 1 dB	-26 dB FS \pm 1 dB
SNR	63 dBA	64 dBA	64 dBA
Current	185 μ A	430 μ A	550 μ A
AOP	120 dB SPL	120 dB SPL	120 dB SPL
Clock	400 – 800 kHz	1.0 – 3.3 MHz	4.1 – 4.8 MHz

- 3.5 × 2.65 × 0.98 mm surface-mount package
- Low power: 550 μ A in Ultrasonic Mode, 185 μ A in Low-Power Mode
- Extended ultrasonic frequency response to 85 kHz
- Sleep Mode: 12 μ A
- High power supply rejection (PSR): -97 dB FS
- Fourth-order Σ - Δ modulator
- Digital pulse density modulation (PDM) output
- Compatible with Sn/Pb and Pb-free solder processes
- RoHS/WEEE compliant

FUNCTIONAL BLOCK DIAGRAM



ORDERING INFORMATION

PART	TEMP RANGE	PACKAGING
ICS-41352	-40°C to +85°C	13" Tape and Reel

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SPECIFICATIONS

TABLE 1. ACOUSTICAL/ELECTRICAL CHARACTERISTICS – GENERAL

T_A = 25°C, V_{DD} = 1.8V to 3.3V, SCK = 2.4 MHz, C_{LOAD} = 30 pF unless otherwise noted. Typical specifications are not guaranteed.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
PERFORMANCE						
Directionality		Omni				
Output Polarity	Input acoustic pressure vs. output data	Non-Inverted				
Supply Voltage (V _{DD})		1.65		3.63	V	
Sleep Mode Current (I _s)	SCK < 200 kHz		20		μA	

TABLE 2. ACOUSTICAL/ELECTRICAL CHARACTERISTICS – ULTRASONIC MODE

T_A = 25°C, V_{DD} = 1.8V to 3.3V, SCK = 4.8 MHz, 25× decimation, C_{LOAD} = 30 pF unless otherwise noted. Typical specifications are not guaranteed.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Sensitivity	1 kHz, 94 dB SPL	-27	-26	-25	dB FS	1, 2
Signal-to-Noise Ratio (SNR)	20 kHz bandwidth, A-weighted		64		dB	
Equivalent Input Noise (EIN)	20 kHz bandwidth, A-weighted		30		dB SPL	
Dynamic Range	Derived from EIN and acoustic overload point		90		dB	
Total Harmonic Distortion (THD)	105 dB SPL		0.2	1	%	
Power Supply Rejection (PSR)	217 Hz, 100 mV p-p square wave superimposed on V _{DD} = 1.8V, A-weighted		-94		dB FS	
Power Supply Rejection—Swept Sine	1 kHz sine wave		-104		dB FS	
Acoustic Overload Point	10% THD		120		dB SPL	
Supply Current (I _s)	V _{DD} = 1.8V, no load		550	600	μA	

Note 1: Sensitivity is relative to the RMS level of a sine wave with positive amplitude equal to 100% 1s density and negative amplitude equal to 0% 1s density.

Note 2: The sensitivity shall not deviate more than 1.0 dB from its initial value after reliability tests.

TABLE 3. ACOUSTICAL/ELECTRICAL CHARACTERISTICS – STANDARD MODE

T_A = 25°C, VDD = 1.8V to 3.3V, SCK = 2.4 MHz, 50× decimation, C_{LOAD} = 30 pF unless otherwise noted. Typical specifications are not guaranteed.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Sensitivity	1 kHz, 94 dB SPL	-27	-26	-25	dB FS	1, 2
Signal-to-Noise Ratio (SNR)	20 kHz bandwidth, A-weighted		64		dB	
Equivalent Input Noise (EIN)	20 kHz bandwidth, A-weighted		30		dB SPL	
Acoustic Dynamic Range	Derived from EIN and acoustic overload point		90		dB	
Digital Dynamic Range	Derived from EIN and full-scale acoustic level		90		dB	
Total Harmonic Distortion (THD)	105 dB SPL		0.2	1	%	
Power Supply Rejection (PSR)	217 Hz, 100 mV p-p square wave superimposed on VDD = 1.8V, A-weighted		-97		dB FS	
Power Supply Rejection—Swept Sine	1 kHz sine wave		-104		dB FS	
Acoustic Overload Point	10% THD		120		dB SPL	
Supply Current (I _s)	V _{DD} = 1.8V, no load		430	500	μA	

Note 1: Sensitivity is relative to the RMS level of a sine wave with positive amplitude equal to 100% 1s density and negative amplitude equal to 0% 1s density.

Note 2: The sensitivity shall not deviate more than 1.0 dB from its initial value after reliability tests.

TABLE 4. ACOUSTICAL/ELECTRICAL CHARACTERISTICS – LOW-POWER MODE

T_A = 25°C, VDD = 1.8V to 3.3V, SCK = 768 kHz, 50× decimation, C_{LOAD} = 30 pF unless otherwise noted. Typical specifications are not guaranteed.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Sensitivity	1 kHz, 94 dB SPL	-27	-26	-25	dB FS	1, 2
Signal-to-Noise Ratio (SNR)	8 kHz bandwidth, A-weighted		63		dB	
Equivalent Input Noise (EIN)	8 kHz bandwidth, A-weighted		31		dB SPL	
Dynamic Range	Derived from EIN and acoustic overload point		89		dB	
Total Harmonic Distortion (THD)	105 dB SPL		0.2	1	%	
Power Supply Rejection (PSR)	217 Hz, 100 mV p-p square wave superimposed on VDD = 1.8V, A-weighted		-97		dB FS	
Power Supply Rejection—Swept Sine	1 kHz sine wave		-98		dB FS	
Acoustic Overload Point	10% THD		120		dB SPL	
Supply Current (I _s)	V _{DD} = 1.8V, no load		185	225	μA	

Note 1: Sensitivity is relative to the RMS level of a sine wave with positive amplitude equal to 100% 1s density and negative amplitude equal to 0% 1s density.

Note 2: The sensitivity shall not deviate more than 1.0 dB from its initial value after reliability tests.

TABLE 5. DIGITAL INPUT/OUTPUT CHARACTERISTICS

T_A = 25°C, 1.8V < V_{DD} < 3.3V, unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input Voltage High (V _{IH})		0.65 x V _{DD}			V	
Input Voltage Low (V _{IL})				0.35 x V _{DD}	V	
Output Voltage High (V _{OH})	I _{LOAD} = 0.5 mA	0.7 x V _{DD}	V _{DD}		V	
Output Voltage Low (V _{OL})	I _{LOAD} = 0.5 mA		0	0.3 x V _{DD}	V	
Output DC Offset	Percent of full scale		3		%	
Latency			<30		µs	

TABLE 6. PDM DIGITAL INPUT/OUTPUT

T_A = 25°C, 1.8V < V_{DD} < 3.3V, unless otherwise noted.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
MODE SWITCHING						
Sleep Time	Time from f _{CLK} falling <200 kHz			1	ms	
Wake-Up Time	Ultrasonic & Standard modes, Sleep Mode to f _{CLK} >1 MHz, output within 0.5 dB of final sensitivity, power on			20	ms	
Wake-Up Time	Low-Power Mode, Sleep Mode to f _{CLK} >400 kHz, output within 0.5 dB of final sensitivity, power on			20	ms	
Switching time	Between Low-Power and Standard Modes			10	ms	
Switching time	Between Low-Power and Ultrasonic Modes			10	ms	
INPUT						
t _{CLKIN}	Input clock period	208		2500	ns	
Clock Frequency (CLK)	Sleep Mode			200	kHz	
	Low-Power Mode	400		800	kHz	
	Standard Mode	1.0		3.3	MHz	
	Ultrasonic Mode	4.1		4.8	MHz	
Clock Duty Cycle	f _{CLK} <3.3 MHz	40		60	%	
	f _{CLK} >4.1 MHz	48		52	%	
t _{RISE}	CLK rise time (10% to 90% level)			25	ns	1
t _{FALL}	CLK fall time (90% to 10% level)			25	ns	1
OUTPUT						
T _{1OUTEN}	DATA1 (right) driven after falling clock edge	50			ns	
T _{1OUTDIS}	DATA1 (right) disabled after rising clock edge	5		40	ns	
T _{2OUTEN}	DATA2 (left) driven after rising clock edge	50			ns	
T _{2OUTDIS}	DATA2 (left) disabled after falling clock edge	5		40	ns	

Note 1: Guaranteed by design

TIMING DIAGRAM

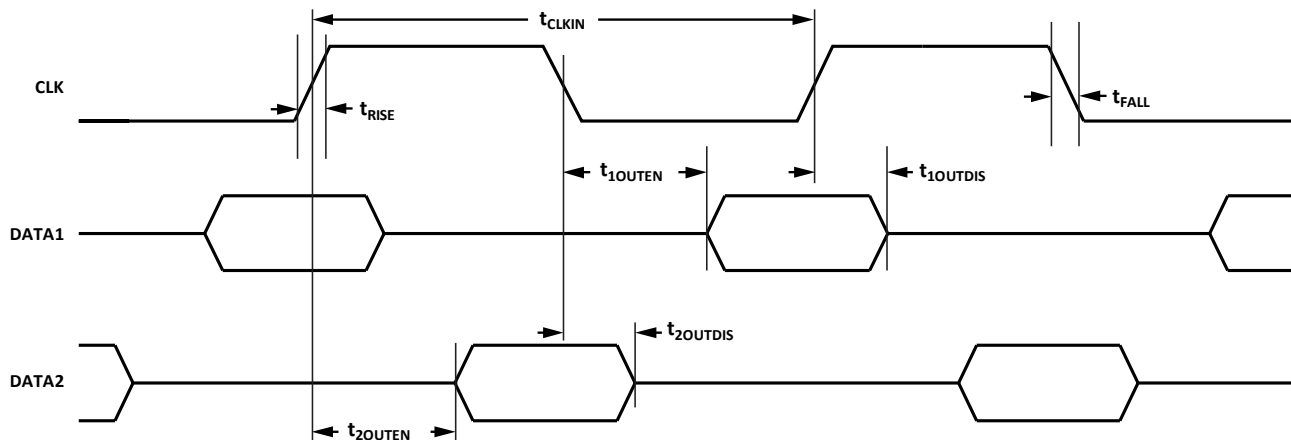


Figure 1. Pulse Density Modulated Output Timing

ABSOLUTE MAXIMUM RATINGS

Stress above those listed as Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these conditions is not implied. Exposure to the absolute maximum ratings conditions for extended periods may affect device reliability.

TABLE 7. ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING
Supply Voltage (V _{DD})	-0.3V to +3.63V
Digital Pin Input Voltage	-0.3V to V _{DD} + 0.3V or 3.63V, whichever is less
Sound Pressure Level	160 dB
Mechanical Shock	10,000g
Vibration	Per MIL-STD-883 Method 2007, Test Condition B
Temperature Range	
Biased	-40°C to +85°C
Storage	-55°C to +150°C

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

SOLDERING PROFILE

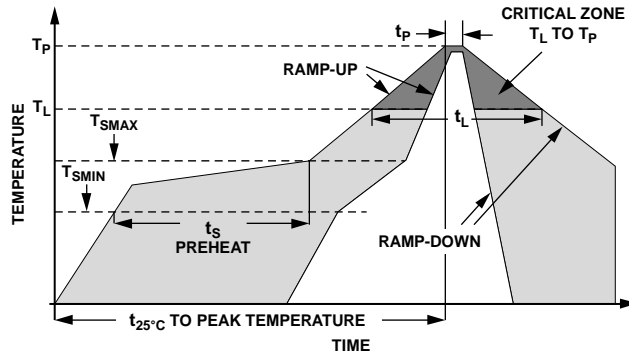


Figure 2. Recommended Soldering Profile Limits

TABLE 8. RECOMMENDED SOLDERING PROFILE*

PROFILE FEATURE		Sn63/Pb37	Pb-Free
Average Ramp Rate (T_L to T_P)		1.25°C/sec max	1.25°C/sec max
Preheat	Minimum Temperature (T_{SMIN})	100°C	100°C
	Minimum Temperature (T_{SMIN})	150°C	200°C
	Time (T_{SMIN} to T_{SMAX}), t_s	60 sec to 75 sec	60 sec to 75 sec
Ramp-Up Rate (T_{SMAX} to T_L)		1.25°C/sec	1.25°C/sec
Time Maintained Above Liquidous (t_L)		45 sec to 75 sec	~50 sec
Liquidous Temperature (T_L)		183°C	217°C
Peak Temperature (T_P)		215°C +3°C/-3°C	260°C +0°C/-5°C
Time Within +5°C of Actual Peak Temperature (t_p)		20 sec to 30 sec	20 sec to 30 sec
Ramp-Down Rate		3°C/sec max	3°C/sec max
Time +25°C ($t_{25^\circ\text{C}}$) to Peak Temperature		5 min max	5 min max

*The reflow profile in

Table 8 is recommended for board manufacturing with InvenSense MEMS microphones. All microphones are also compatible with the J-STD-020 profile

PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS

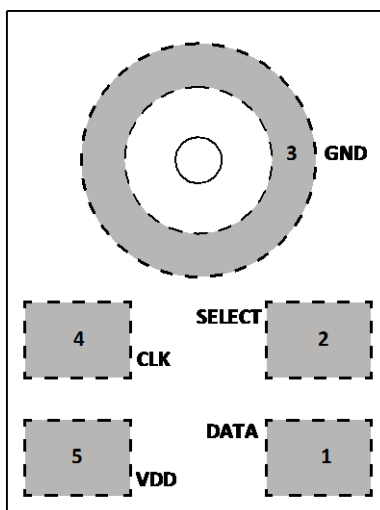


Figure 3. Pin Configuration (Top View, Terminal Side Down)

TABLE 9. PIN FUNCTION DESCRIPTIONS

PIN	NAME	FUNCTION
1	DATA	Digital Output Signal (DATA1 or DATA2)
2	SELECT	Left Channel or Right Channel Select: DATA 1 (right): SELECT tied to GND DATA 2 (left): SELECT tied to VDD
3	GND	Ground
4	CLK	Clock Input to Microphone
5	VDD	Power Supply. For best performance and to avoid potential parasitic artifacts, place a 0.1 μ F (100 nF) ceramic type X7R capacitor between Pin 5 (VDD) and ground. Place the capacitor as close to Pin 5 as possible.

TYPICAL PERFORMANCE CHARACTERISTICS

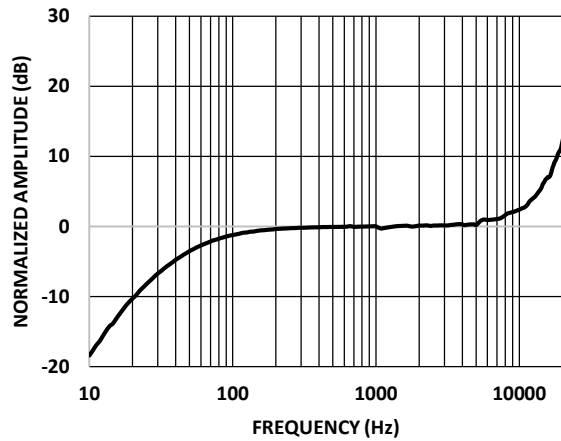


Figure 4. Typical Frequency Response

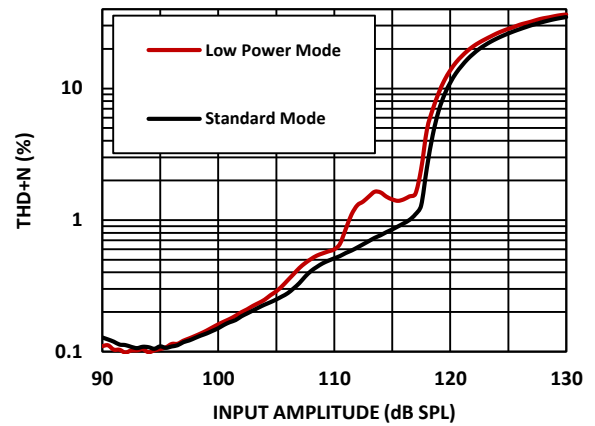


Figure 5. THD + N vs. Input Level

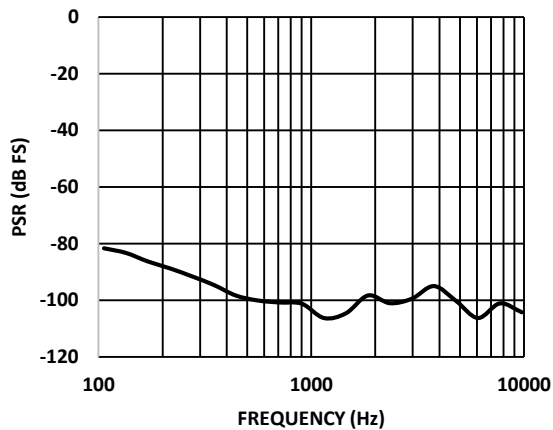


Figure 6. Power Supply Rejection (PSR) vs. Frequency

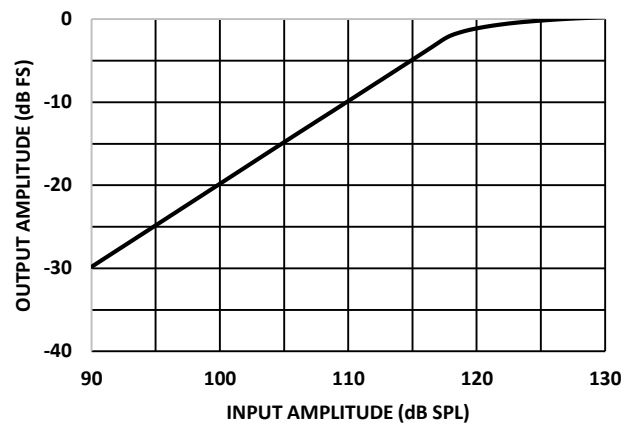


Figure 7. Linearity

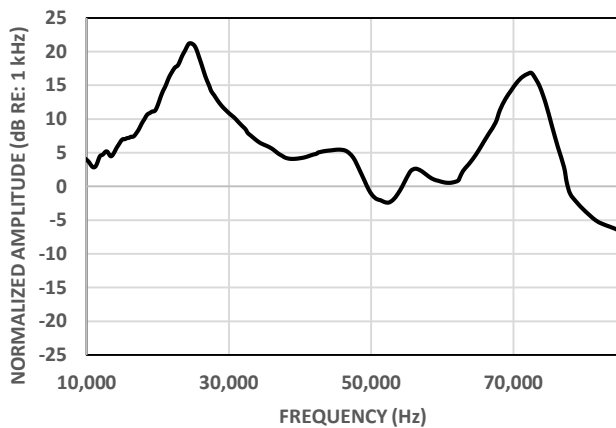


Figure 8. Typical Ultrasonic Frequency Response

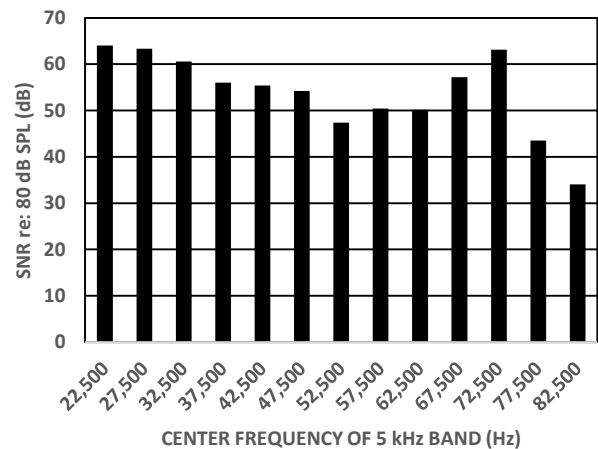


Figure 9. Typical Ultrasonic SNR

THEORY OF OPERATION

PDM DATA FORMAT

The output from the DATA pin of the ICS-41352 is in pulse density modulated (PDM) format. This data is the 1-bit output of a fourth-order Σ - Δ modulator. The data is encoded so that the left channel is clocked on the falling edge of CLK, and the right channel is clocked on the rising edge of CLK. After driving the DATA signal high or low in the appropriate half frame of the CLK signal, the DATA driver of the microphone tristates. In this way, two microphones, one set to the left channel and the other to the right, can drive a single DATA line. See Figure 1 for a timing diagram of the PDM data format; the DATA1 and DATA2 lines shown in this figure are two halves of the single physical DATA signal. Figure 10 shows a diagram of the two stereo channels sharing a common DATA line.

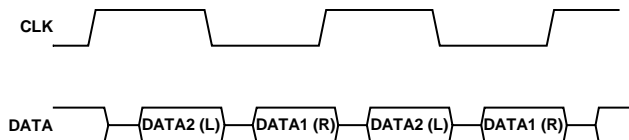


Figure 10. Stereo PDM Format

If only one microphone is connected to the DATA signal, the output is only clocked on a single edge (Figure 11). For example, a left channel microphone is never clocked on the rising edge of CLK. In a single microphone application, each bit of the DATA signal is typically held for the full CLK period until the next transition because the leakage of the DATA line is not enough to discharge the line while the driver is tristated.

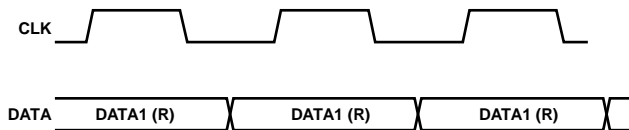


Figure 11. Mono PDM Format

See Table 10 for the channel assignments according to the logic level on the SELECT pin.

TABLE 10. ICS-41352 CHANNEL SETTING

SELECT Pin Setting	Channel
Low (tie to GND)	Right (DATA1)
High (tie to VDD)	Left (DATA2)

For PDM data, the density of the pulses indicates the signal amplitude. A high density of high pulses indicates a signal near positive full scale, and a high density of low pulses indicates a signal near negative full scale. A perfect zero (dc) audio signal shows an alternating pattern of high and low pulses.

The output PDM data signal has a small dc offset of about 3% of full scale. A high-pass filter in the codec that is connected to the digital microphone and does not affect the performance of the microphone typically removes this dc signal.

PDM MICROPHONE SENSITIVITY

The sensitivity of a PDM output microphone is specified with the unit dB FS (decibels relative to digital full scale). A 0 dB FS sine wave is defined as a signal whose peak just touches the full-scale code of the digital word (see Figure 12). This measurement convention also means that signals with a different crest factor may have an RMS level higher than 0 dB FS. For example, a full-scale square wave has an RMS level of 3 dB FS.

This definition of a 0 dB FS signal must be understood when measuring the sensitivity of the ICS-41352. A 1 kHz sine wave at a 94 dB SPL acoustic input to the ICS-41352 results in an output signal with a -26 dB FS level. The output digital word peaks at -26 dB below the digital full-scale level. A common misunderstanding is that the output has an RMS level of -29 dB FS; however, this is not true because of the definition of the 0 dB FS sine wave.

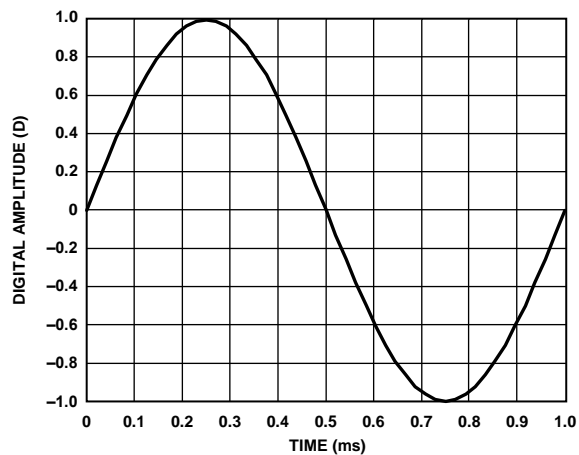


Figure 12. 1 kHz, 0 dB FS Sine Wave

There is not a commonly accepted unit of measurement to express the instantaneous level, as opposed to the RMS level of the signal, of a digital signal output from the microphone. Some measurement systems express the instantaneous level of an individual sample in units of D, where 1.0 D is digital full scale. In this case, a -26 dB FS sine wave has peaks at 0.05 D.

APPLICATIONS INFORMATION

LOW POWER MODE

Low Power Mode (LPM) enables the ICS-41352 to be used in an AlwaysOn listening mode for keyword spotting and ambient sound analysis. The ICS-41352 will enter LPM when the frequency of SCK is between 400 and 800 kHz. In this mode, the microphone consumes only 185 μ A while retaining high electro-acoustic performance.

When one microphone is in LPM for AlwaysOn listening, a second microphone sharing the same data line may be powered down. In this case, where one microphone is powered up and another is powered down by disabling the VDD supply or in sleep mode by reducing the frequency of a separate clock source, the disabled microphone does not present a load to the signal on the LPM microphone's DATA pin.

DYNAMIC RANGE CONSIDERATIONS

The full-scale digital output (0 dB FS) of the ICS-41352 is mapped to an acoustic input of 120 dB SPL. The microphone clips (THD = 10%) at 120 dB SPL (see Figure 5); however, it continues to output an increasingly distorted signal above that point. The peak output level, which is controlled by the modulator, limits at 0 dB FS (see Figure 7).

To fully use the 90 dB dynamic range of the output data of the ICS-41352 in a design, the digital signal processor (DSP), analog-to-digital converter (ADC), or codec circuit following it must be chosen carefully. The decimation filter that inputs the PDM signal from the ICS-41352 must have a dynamic range sufficiently better than the dynamic range of the microphone so that the overall noise performance of the system is not degraded. If the decimation filter has a dynamic range of 10 dB better than the microphone, the overall system noise only degrades by 0.4 dB. This 100 dB filter dynamic range requires the filter to have at least 17-bit resolution.

CONNECTING PDM MICROPHONES

A PDM output microphone is typically connected to a codec with a dedicated PDM input. This codec separately decodes the left and right channels and filters the high sample rate modulated data back to the audio frequency band. This codec also generates the clock for the PDM microphones or is synchronous with the source that is generating the clock. Figure 13 and Figure 14 show mono and stereo connections of the ICS-41352 to a codec. The mono connection shows an ICS-41352 set to output data on the right channel. To output on the left channel, tie the SELECT pin to VDD instead of tying it to GND.

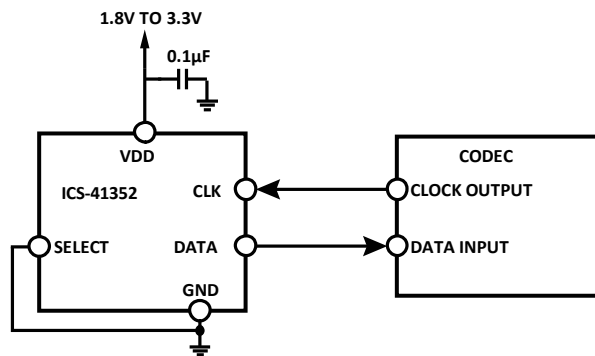


Figure 13. Mono PDM Microphone (Right Channel) Connection to Codec

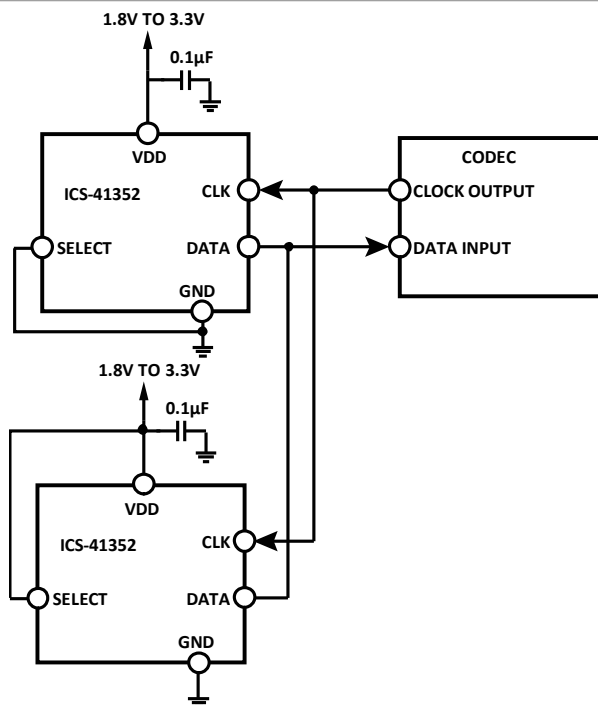


Figure 14. Stereo PDM Microphone Connection to Codec

Decouple the VDD pin of the ICS-41352 to GND with a 0.1 µF capacitor. Place this capacitor as close to VDD as the printed circuit board (PCB) layout allows.

Do not use a pull-up or pull-down resistor on the PDM data signal line because it can pull the signal to an incorrect state during the period that the signal line is tristated.

The DATA signal does not need to be buffered in normal use when the ICS-41352 microphone(s) is placed close to the codec on the PCB. If the DATA signal must be driven over a long cable (>15 cm) or other large capacitive load, a digital buffer may be required. Only use a signal buffer on the DATA line when one microphone is in use or after the point where two microphones are connected (see Figure 15). The DATA output of each microphone in a stereo configuration cannot be individually buffered because the two buffer outputs cannot drive a single signal line. If a buffer is used, take care to select one with low propagation delay so that the timing of the data connected to the codec is not corrupted.

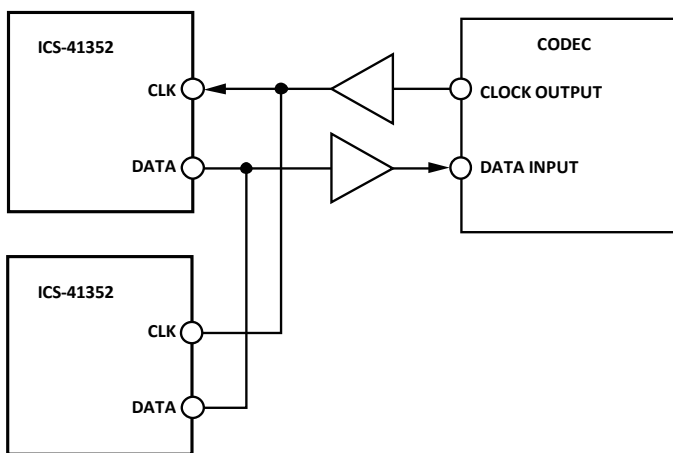


Figure 15. Buffered Connections Between Stereo ICS-41352s and a Codec

When long wires are used to connect the codec to the ICS-41352, a source termination resistor can be used on the clock output of the codec instead of a buffer to minimize signal overshoot or ringing. Match the value of this resistor to the characteristic impedance of the CLK trace on the PCB. Depending on the drive capability of the codec clock output, a buffer may still be needed, as shown in Figure 15.

ULTRASOUND APPLICATIONS

In its Ultrasonic Mode, the ICS-41352 functions as a low-noise ultrasonic sensor, as well as an audio band sensor. The microphone's ultrasonic performance will depend on the clock frequency, the low pass decimation filter, the strength of the ultrasonic signal being sensed, and the design of the acoustic port that is coupled to the microphone. The acoustic port design is especially important at higher frequencies, because the size of the port itself is on the order of $\frac{1}{4}$ the wavelength of sound and the acoustic mass loading will be significant. These will both contribute to the port having a considerable effect on the acoustic system's response.

SLEEP MODE

The microphone enters sleep mode when the clock frequency falls below 200 kHz. In this mode, the microphone data output is in a high impedance state. The current consumption in sleep mode is less than 20 μ A.

The ICS-41352 enters sleep mode within 1 ms of the clock frequency falling below 200 kHz. The microphone wakes up from sleep mode and begins to output data within 20 ms of when the clock becomes active.

START-UP TIME

The start-up time of the ICS-41352 is less than 20 ms. The PDM data from the microphone is valid to be used as soon as the data is being output.

SUPPORTING DOCUMENTS

For additional information, see the following documents.

APPLICATION NOTES

AN-000048, *PDM Digital Output MEMS Microphone Flex Evaluation Board User Guide*

AN-100, MEMS Microphone Handling and Assembly Guide

AN-1003: Recommendations for Mounting and Connecting the Invensense, Bottom-Ported MEMS Microphones

AN-1112: Microphone Specifications Explained

AN-1124: Recommendations for Sealing InvenSense Bottom-Port MEMS Microphones from Dust and Liquid Ingress

AN-1140: Microphone Array Beamforming

PCB DESIGN AND LAND PATTERN LAYOUT

The recommended PCB land pattern for the ICS-41352 is a 1:1 ratio of the solder pads on the microphone package, as shown in Figure 16. Avoid applying solder paste to the sound hole in the PCB. A suggested solder paste stencil pattern layout is shown in Figure 17.

The response of the ICS-41352 is not affected by the PCB hole size as long as the hole is not smaller than the sound port of the microphone (0.375 mm in diameter). A 0.5 mm to 1 mm diameter for the hole is recommended. Take care to align the hole in the microphone package with the hole in the PCB. The exact degree of the alignment does not affect the microphone performance as long as the holes are not partially or completely blocked.

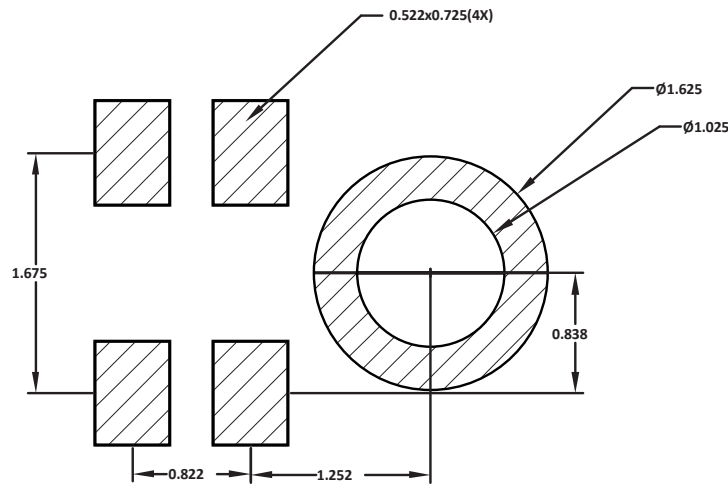


Figure 16. Recommended PCB Land Pattern Layout

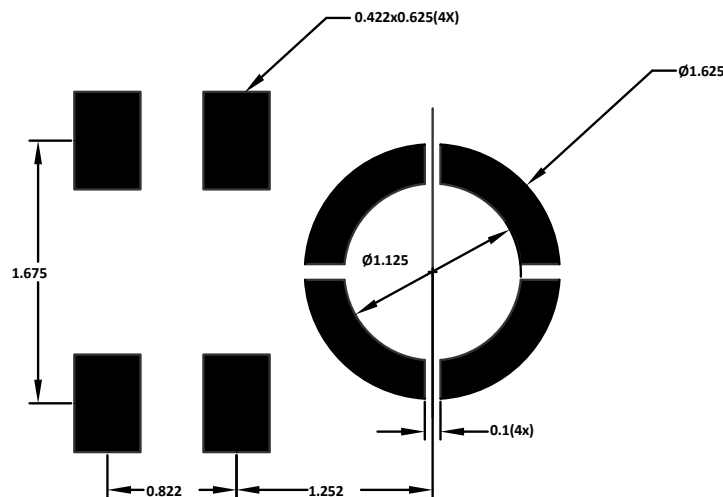


Figure 17. Suggested Solder Paste Stencil Pattern Layout

PCB MATERIAL AND THICKNESS

The audio performance of the ICS-41352 is not affected by PCB thickness. The ICS-41352 can be mounted on either a rigid or flexible PCB. A flexible PCB with the microphone can be attached directly to the device housing with an adhesive layer. This mounting method offers a reliable seal around the sound port while providing the shortest acoustic path for good sound quality.

HANDLING INSTRUCTIONS

PICK AND PLACE EQUIPMENT

The MEMS microphone can be handled using standard pick-and-place and chip shooting equipment. Take care to avoid damage to the MEMS microphone structure as follows:

- Use a standard pickup tool to handle the microphone. Because the microphone hole is on the bottom of the package, the pickup tool can make contact with any part of the lid surface.
- Do not pick up the microphone with a vacuum tool that makes contact with the bottom side of the microphone. Do not pull air out of or blow air into the microphone port.
- Do not use excessive force to place the microphone on the PCB.

REFLOW SOLDER

For best results, the soldering profile must be in accordance with the recommendations of the manufacturer of the solder paste used to attach the MEMS microphone to the PCB. It is recommended that the solder reflow profile not exceed the limit conditions specified in Figure 2 and Table 8.

BOARD WASH

When washing the PCB, ensure that water does not make contact with the microphone port. Do not use blow-off procedures or ultrasonic cleaning.

OUTLINE DIMENSIONS

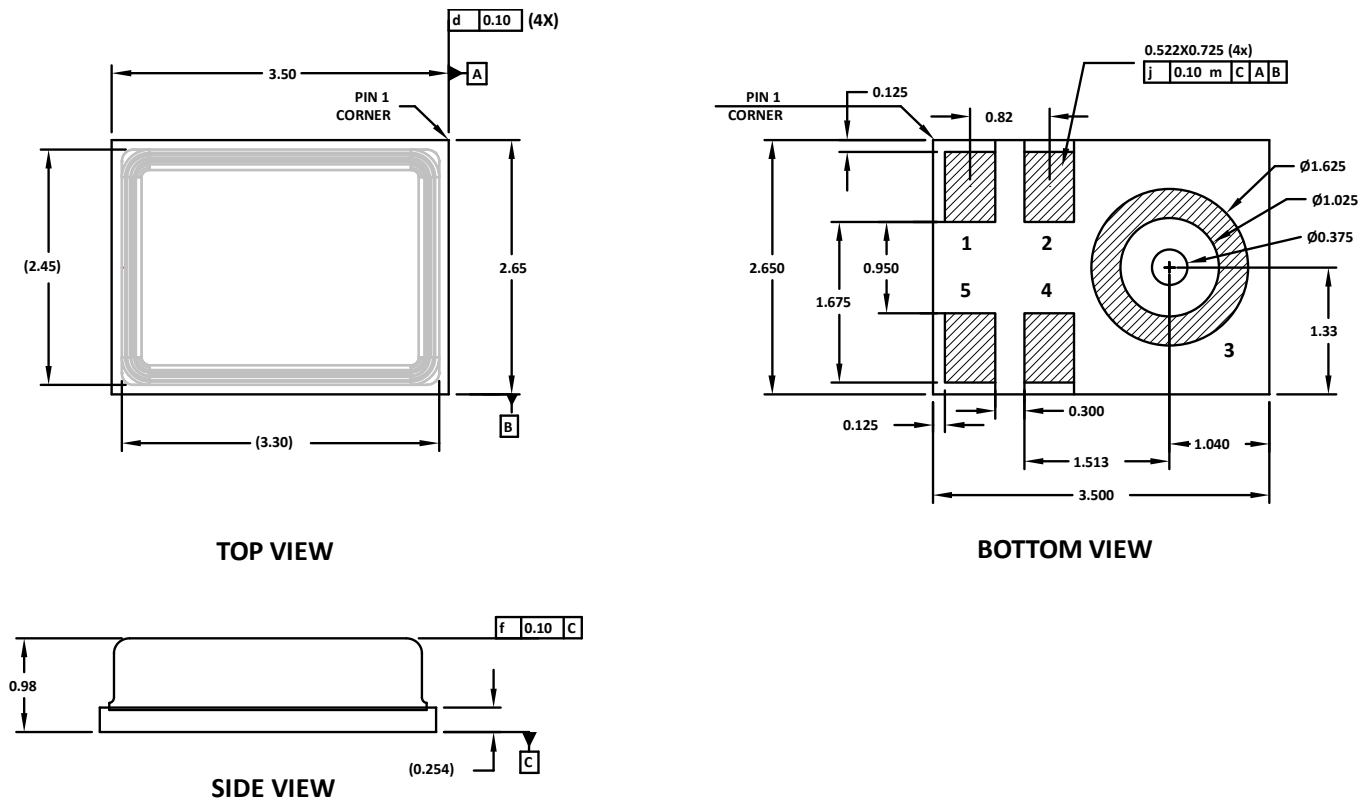


Figure 18. 5-Terminal Chip Array Small Outline No Lead Cavity [LGA_CAV]
 3.5 mm × 2.65 mm × 0.98 mm Body
 Dimensions shown in millimeters
 Dimension tolerance is ±0.15 mm unless otherwise specified

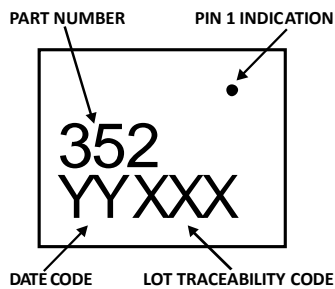


Figure 19. Package Marking Specification (Top View)

ORDERING GUIDE

PART	TEMP RANGE	PACKAGE	QUANTITY	PACKAGING
ICS-41352	-40°C to +85°C	5-Terminal LGA_CAV	5,000	13" Tape and Reel
EV_IC3-41352-FX	—	Evaluation Board	—	

REVISION HISTORY

REVISION DATE	REVISION	DESCRIPTION
9/30/2016	1.0	Initial version

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